Input
2.0V, 42V peak

TP1
VIN
GND
TP2
Optional Bulk Cap
J1
C1 150μF

L1 10μH
TP3
C2 3.3μF
C3 3.3μF
C4
D1 MBRD660
C6 3.3μF

Q1 CSD18534Q5A
R3 120mV
R4 1.0k
R5 10m

TP4
VOUT
GND
TP5

Notes
- R10 for test purpose only
- Built on PCB PMP5171 Rev.A
- Parts with RefDes > 100 added

Output
8.0V / 0.75A continuous @ 2..5V input
8.0V / 1.0A peak @ 2..5V input
8.0V @ 1.5A continuous @ 5..20V input
8.0V @ 2.5A peak @ 5..20V input
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